



FY18 MicReD New Products Introduction

- ☞ T3Ster 從 2000年開發至今已有17年的時間，憑藉著強大的熱阻量測功能及數據解析而被國內外廣大客戶所信賴及進行產品研發使用。
- ☞ 在今年，MicReD針對T3Ster進行不同的改款，以提供客戶可以有更多的選擇。

- ☞ MicReD FY18 新產品如下：

- Booster 240A/11V
- Dyn-TIM S
- T3Ster S
- T3Ster IC
- In-line Volume Test

Not only T3Ster, you can have more choose !

Booster 240A/11V



❖ 新型Booster +PSU 增壓穩壓系統: 240A/11V

❖ 簡易規格:

- Heating current: 1x10..240A/10V, not grounded
- Sensing current: 1x -1A..1A, grounded
- Gate driver: 4x -10..25V, not grounded
- 4U high main box + 2x1U power supply;
- Complete solution: 2x120A/12V power supplies included in the bundle

- Easy measurement of IGBT half-bridges - both the gate drivers and the heating current sources are floating, not grounded
- Can heat MOSFET on open channel and measure on body diode
- Built-in $R_{ds,on}$ generator for one device (+ LV booster compatible rear connector for external VCB generator)



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Dyn-TIM S



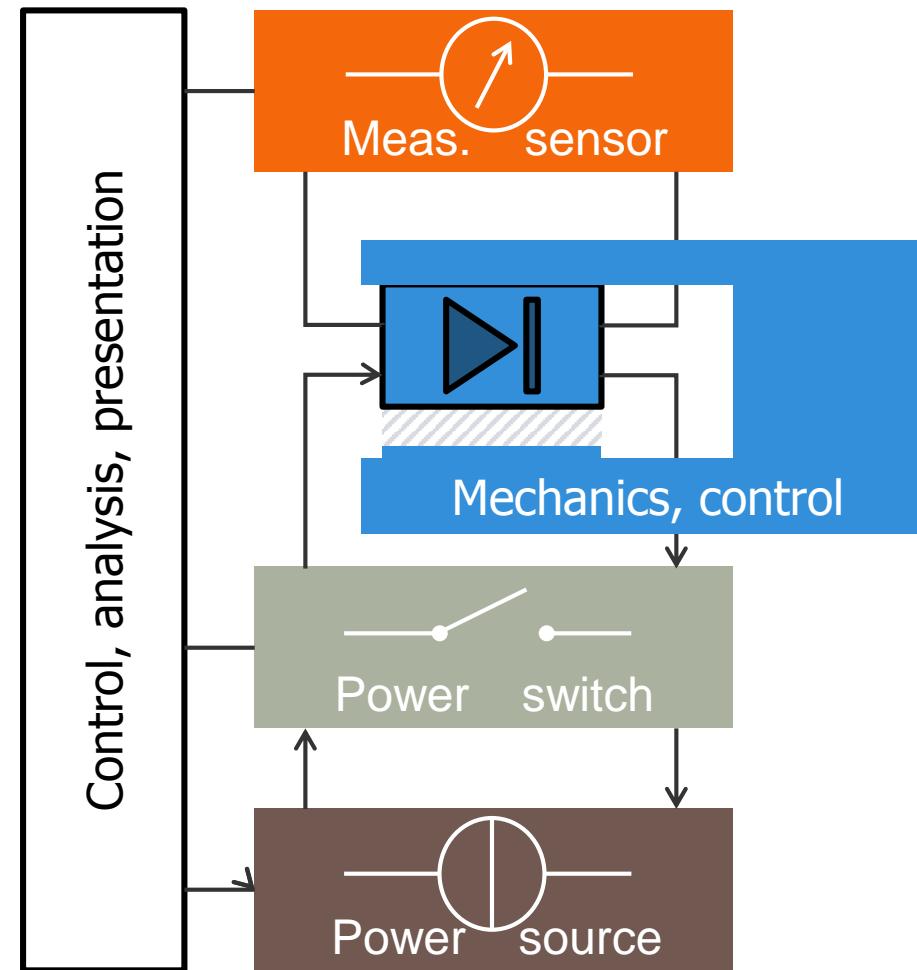
- 單獨且完整的散熱TIM材導熱係數量測平台，不需再倚靠T3Ster的輔助即可單獨完成量測。

Measuring bulk thermal conductivity of thermal interface materials by varying thickness

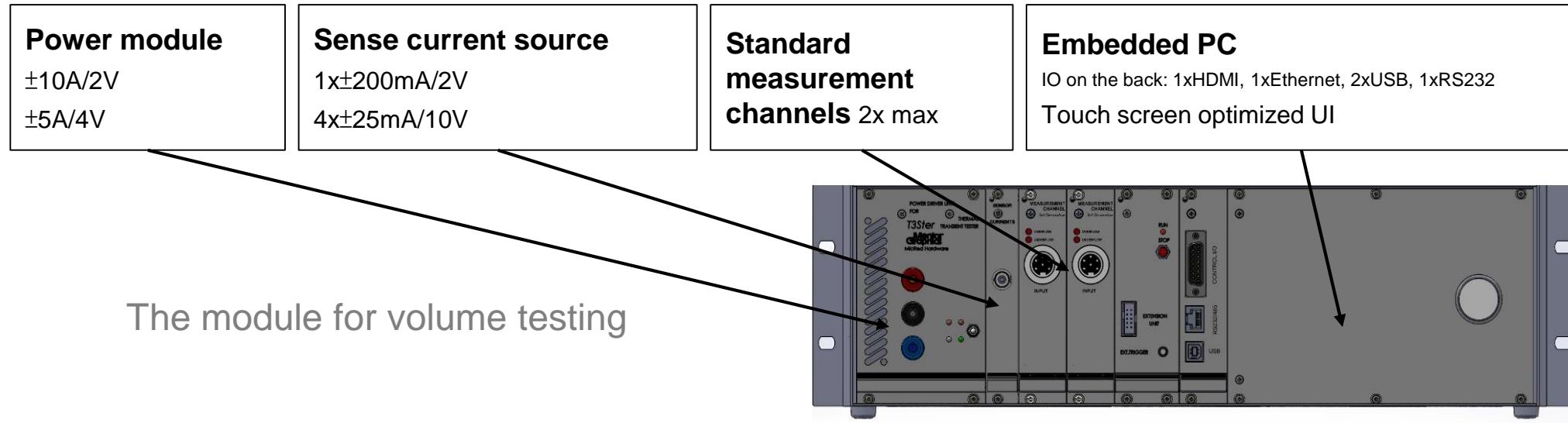
DynTIM S includes:

- Mechanics for thickness control
- Diode for heating and sensing
- Control electronics
- Heating and sensing circuits

No other MicReD HW is needed



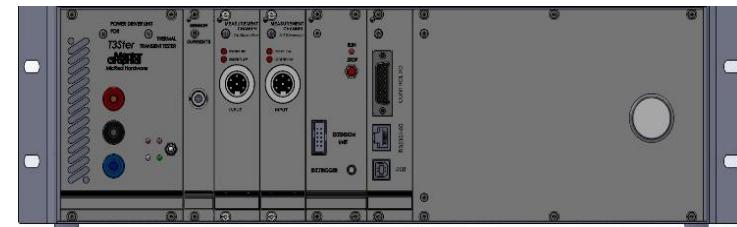
T3Ster S



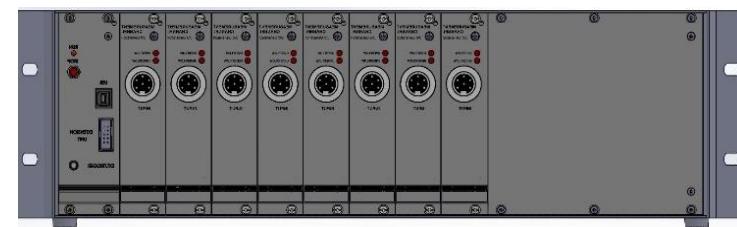
❖ 簡易規格書:

1. 和T3Ster大小相同，配置兩個量測Channel，內建工業電腦(觸碰螢幕)
2. 電流輸出規格可自行選配: Heating Current : 10A/2V 或 5A/4V
Sense current: $1 \times 200mA/2V$ 或 $4 \times 25mA/10V$
3. 比起T3Ster更親民的價格
4. 可由內建工業電腦直接針對量測進行完整的設定
5. 可外加附屬量測設備

T3Ster IC

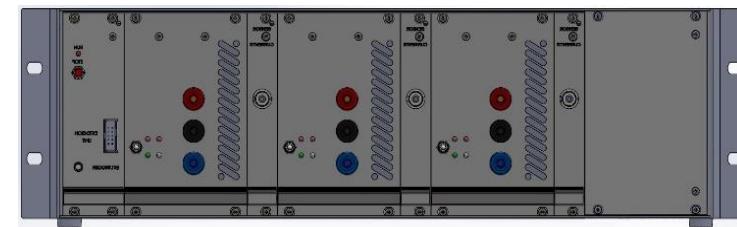


T3Ster S



Sense Box

Up to 8 additional measurement channels



Force box (1 or 2)

3 or 6 additional power and sensor current modules

The module for IC testing

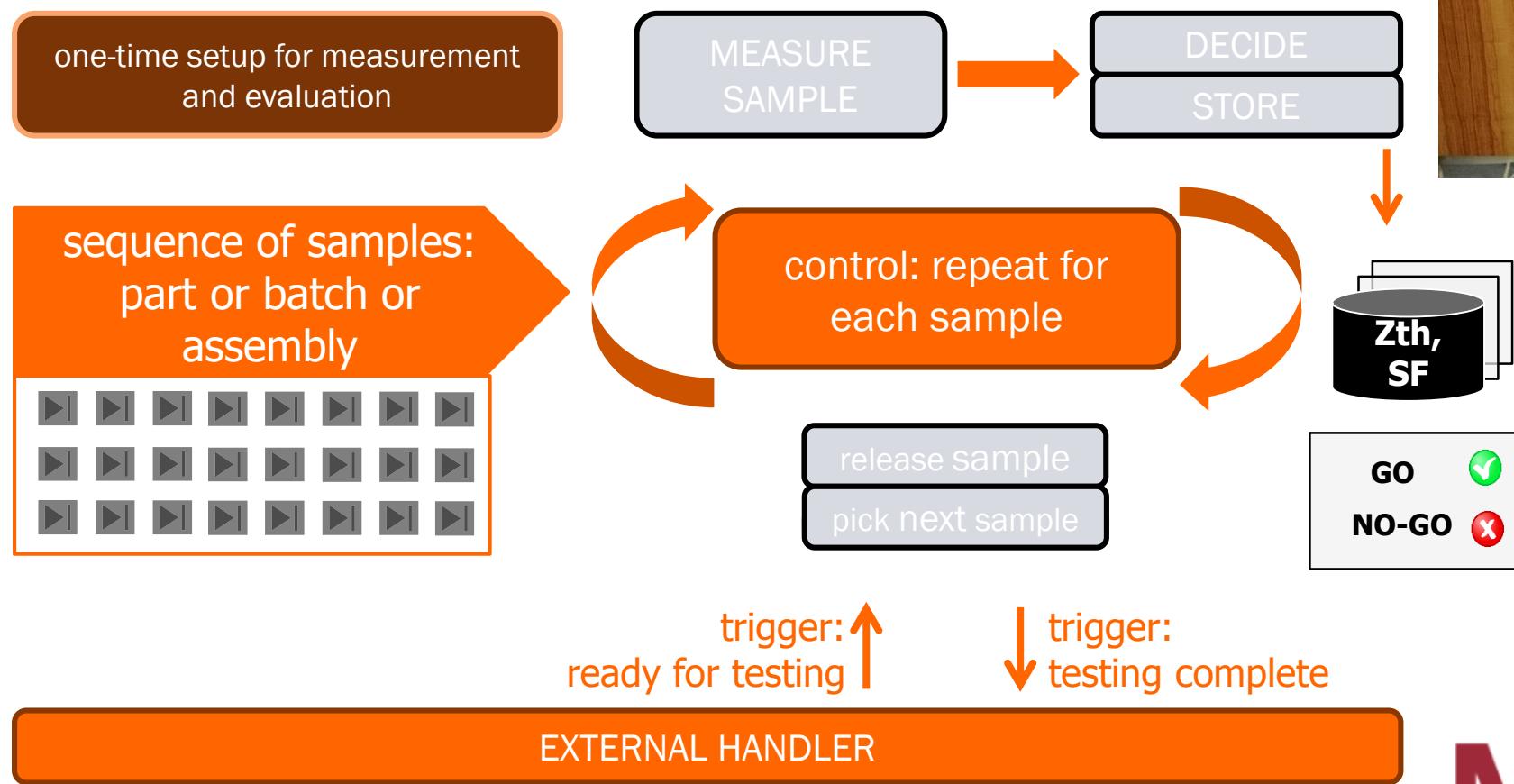
简易規格書:

1. 以T3Ster S為本體進行擴充: 最多可達10個量測Channel，4~7個 force Channel
2. 最大電流輸出: 10A/2V
3. 可針對Multi-chip IC進行量測
4. 暫態熱阻測試

In-line Volume Test System



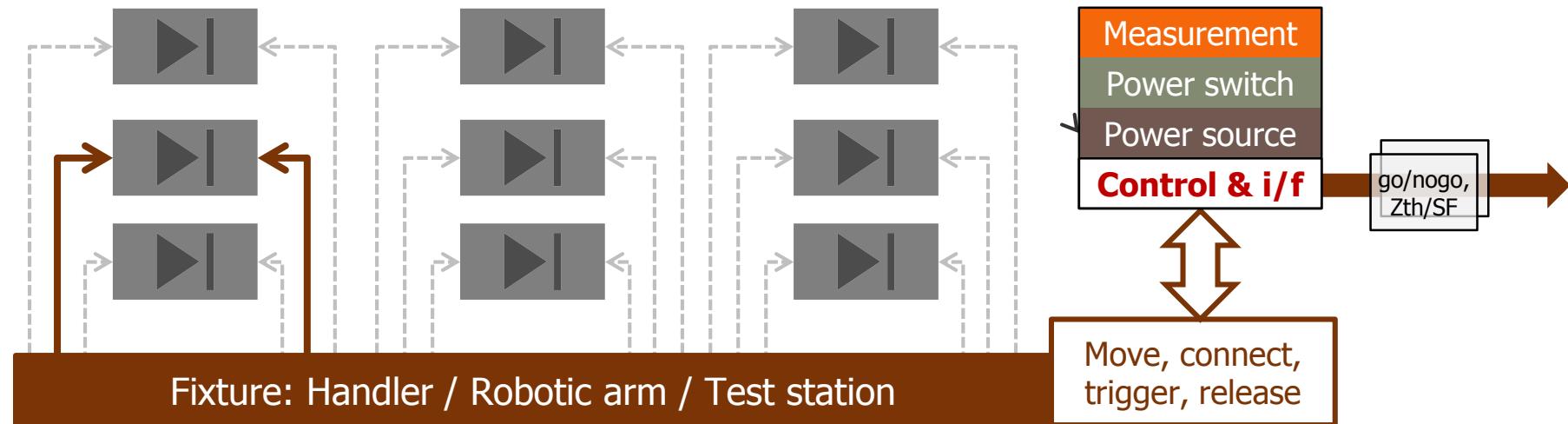
❖ 產品批量檢測設備



In-line Volume Test System



全自動的測試平台



Example: PWT manufacturing
(industrial)

Power circuits are tested for:

- Device issues (die attach)
- Solder quality (cooling)
- Absolute value / deviation

Case is application dependent

Core test process:

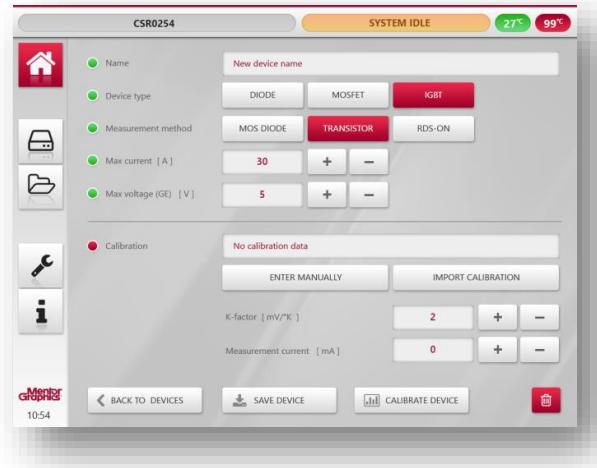
- Starts on trigger
- Powers and Measures
- Release signal after measurement
- Go / no-go or binning decision
- Present results for evaluation

In-line Volume Test System



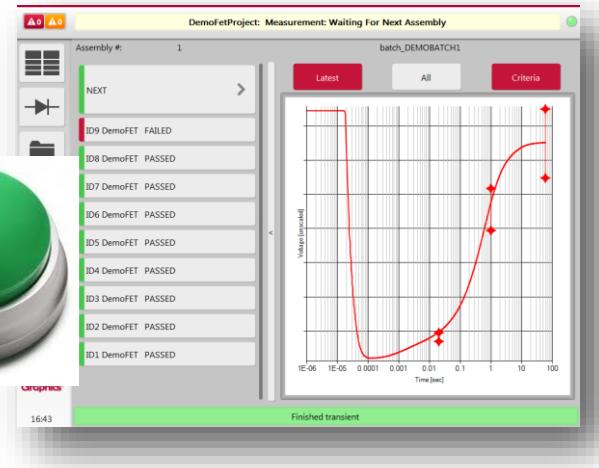
使用者介面

- ❖ 觸碰螢幕 / 和Power Tester相同
- ❖ 可按順序逐步點選所需的量測
- ❖ 圖示說明，容易上手
- ❖ 工程師及操作員皆可使用



全自動化

- ❖ 可重複量測
- ❖ 可大量測試
- ❖ 一鍵啟動
- ❖ 自動分析



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